

UNIRAM TECHNOLOGY, INC, No C-04-1268 VRW  
Plaintiff, ORDER  
v  
MONOLITHIC SYSTEM TECHNOLOGY,  
INC, et al,  
Defendants.

Plaintiff UniRAM Technology, Inc ("UniRAM") owns the two patents-in-suit, which relate to dynamic random access memory ("DRAM") and methods for the manufacture thereof. UniRAM contends that defendants Taiwan Semiconductor Manufacturing Company, LTD and TSMC North America (collectively "TSMC") and Monolithic System Technology, Inc ("MoSys") infringed UniRAM's United States Patent No 6,108,229 (the "'229 patent"). SAC (Doc #16-1). MoSys and TSMC separately denied the allegations and, on counterclaims, sought a declaratory judgment that both the '229 patent and UniRAM's United States Patent No 6,687,148 (the "'148 patent") were invalid,

1 unenforceable and not infringed. MoSys SAC Ans (Doc #23); TSMC SAC  
2 Ans (Doc #27).

3           On October 13, 2005, the court held a claim construction  
4 hearing for disputed terms in both patents pursuant to Markman v  
5 Westview Instruments, Inc, 517 US 370 (1996). Based on the  
6 parties' submission to the court and their arguments at the  
7 hearing, the court issues the following claim construction order.

8           As the court writes principally for the parties, it will  
9 not discuss the details of the inventions or define terms well-  
10 known to those skilled in the art, except as is necessary to  
11 construe the patent claims. Nor will the court recapitulate the  
12 parties' agreed-upon constructions, which can be found in the final  
13 joint claim construction statement. Jt Cl Const (Doc #117), Ex A.

14  
15 I

16           The '229 patent, which issued on August 22, 2000, to Dr  
17 Jeng-Jye Shau ("Shau"), discloses a DRAM cell array that is  
18 manufactured by processes typically used to produce logic devices  
19 such as CPUs and microprocessors. The '148 patent, which issued on  
20 February 3, 2004, to Shau, discloses methods for manufacturing DRAM  
21 cell arrays by processes typically used for producing logic  
22 devices.

23           Although both patents have different claims, they share  
24 the same specification and stem from the same two patent  
25 applications. The '229 patent is a continuation-in-part both of  
26 application no 08/805,290 (issued United States Patent No  
27 5,825,704) and application no 08/653,620 (issued United States  
28 Patent No 5,748,547). The '148 patent is a continuation of

1 application no 09/860,215 (issued United States Patent No  
2 6,504,745), which in turn is a continuation-in-part of application  
3 nos 08/805,290 and 08/653,620, like the '229 patent. In short, the  
4 '148 patent is a "nephew" of the '229 patent.

5 All claims in the '148 patent were allowed after the  
6 patentee amended them in response to an office action rejecting the  
7 claims on enablement and written description grounds. All claims  
8 in the '229 patent were allowed after the patentee withdrew some in  
9 response to an office action requiring restriction of the patent to  
10 one invention.

## 11 II

12 The construction of patent claims is a question of law to  
13 be determined by the court. Markman v Westview Instruments, Inc.,  
14 517 US 370 (1996). The goal of claim construction is "to interpret  
15 what the patentee meant by a particular term or phrase in a claim."  
16 Renishaw PLC v Marposs SpA, 158 F3d 1243, 1249 (Fed Cir 1998). In  
17 doing so, the court looks first to the claim itself:

18 The claims of the patent provide the concise  
19 formal definition of the invention. They are  
20 the numbered paragraphs which "particularly  
21 [point] out and distinctly [claim] the subject  
22 matter which the applicant regards as his  
23 invention." 35 USC § 112. It is to these  
24 wordings that one must look to determine  
25 whether there has been infringement. Courts  
26 can neither broaden nor narrow the claims to  
27 give the patentee something different than what  
28 he has set forth. No matter how great the  
temptations of fairness or policy making,  
courts do not rework claims. They only  
interpret them.

EI Du Pont de Nemours & Co v Phillips Petroleum Co, 849 F2d 1430,  
1433 (Fed Cir 1988).

1           “The claims define the scope of the right to exclude; the  
2 claim construction inquiry, therefore, begins and ends in all cases  
3 with the actual words of the claim.” Renishaw, 158 F3d at 1248.

4           “The words used in the claim are viewed through the viewing glass  
5 of a person skilled in the art.” Brookhill-Wilk 1, LLC v Intuitive  
6 Surgical, Inc, 326 F3d 1215, 1220 (Fed Cir 2003) (citing Tegal Corp  
7 v Tokyo Electron Am, Inc, 257 F3d 1331, 1342 (Fed Cir 2001)).

8           “Absent a special and particular definition created by the patent  
9 applicant, terms in a claim are to be given their ordinary and  
10 accustomed meaning.” York Prods, Inc v Central Tractor Farm &  
11 Family Ctr, 99 F3d 1568, 1572 (Fed Cir 1996). The court may, if  
12 necessary, consult a variety of sources to determine the ordinary  
13 and customary meaning of a claim term, including “the words of the  
14 claims themselves, the remainder of the specification, the  
15 prosecution history, and extrinsic evidence concerning relevant  
16 scientific principles, the meaning of technical terms, and the  
17 state of the art.” Innova/Pure Water, Inc v Safari Water, 381 F3d  
18 1111, 1116 (Fed Cir 2004).

19           The court begins its construction of claim terms by  
20 consulting intrinsic evidence of the meaning of disputed claim  
21 terms, which includes the claims, the specification and the  
22 prosecution history (if in evidence). Lacks Industries, Inc v  
23 McKechnie Vehicle Components USA, Inc, 322 F3d 1335, 1341 (Fed Cir  
24 2003) (citation omitted). “If upon examination of this intrinsic  
25 evidence the meaning of the claim language is sufficiently clear,  
26 resort to ‘extrinsic’ evidence \* \* \* should not be necessary.”  
27 Digital Biometrics, Inc, v Identix, Inc, 149 F3d 1335, 1344 (Fed  
28 Cir 1998). “[I]f after consideration of the intrinsic evidence,

1 there remains doubt as to the exact meaning of the claim terms,  
2 consideration of extrinsic evidence may be necessary to determine  
3 the proper construction." Id. Although extrinsic evidence such as  
4 expert and inventor testimonies, dictionaries and learned treatises  
5 can shed useful light on the relevant art, extrinsic evidence is  
6 "less significant than the intrinsic record in determining the  
7 legally operative meaning of claim language." Phillips v AWH Corp,  
8 415 F3d 1303, 1317 (Fed Cir 2005) (quoting C R Bard, Inc v United  
9 States Surgical Corp, 388 F3d 858, 862 (Fed Cir 2004)) (internal  
10 quotation marks omitted).

11 "[A] court may constrict the ordinary meaning of a claim  
12 term in at least one of four ways[:]" (1) "if the patentee acted as  
13 his own lexicographer and clearly set forth a definition of the  
14 disputed claim in either the specification or prosecution history;"  
15 (2) "if the intrinsic evidence shows that the patentee  
16 distinguished [the] term from prior art on the basis of a  
17 particular embodiment, expressly disclaimed subject matter, or  
18 described a particular embodiment as important to the invention;"  
19 (3) "if the term chosen by the patentee so deprives the claim of  
20 clarity as to require resort to the other intrinsic evidence for a  
21 definite meaning;" or (4) "if the patentee phrased the claim in  
22 step- or means-plus-function format," then "a claim term will cover  
23 nothing more than the corresponding structure or step disclosed in  
24 the specification, as well as equivalents thereto \* \* \*." CCS  
25 Fitness, Inc v Brunswick Corp, 288 F3d 1359, 1366-67 (Fed Cir 2002)  
26 (internal citations and quotation marks omitted).

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1 Limitations from the specification, such as from a  
2 preferred embodiment, cannot be read into the claims unless  
3 expressly intended by the patentee. Teleflex, Inc v Ficosa North  
4 Am Corp, 299 F3d 1313, 1326 (Fed Cir 2002) ("The claims must be  
5 read in view of the specification, but limitations from the  
6 specification are not to be read into the claims."). And "a  
7 construction that excludes a preferred embodiment 'is rarely, if  
8 ever, correct.'" C R Bard, 388 F3d at 865 (citing Vitronics Corp v  
9 Conceptronic, Inc, 90 F3d 1576, 1583 (Fed Cir 1996)).

10 With these legal principles in mind, the court now  
11 construes the disputed claim language in the patents.

### 13 III

#### 14 1. "logic circuit"

15 "Logic circuit" is used in claims 1 and 22 of the '148  
16 patent. UniRAM contends that "logic circuit" means "a high  
17 performance circuit, distinct from the circuits found in a stand-  
18 alone memory device, whose primary design goal is the efficient  
19 performance of logic functions, such as a microprocessor or ASIC."  
20 Jt Cl Const, Ex B at 12. MoSys construes logic circuit as "[a]  
21 circuit outside of the memory array that performs some processing  
22 or controlling function." *Id.* TSMC adopts the even broader  
23 definition, "[a] circuit that performs processing or controlling  
24 functions." *Id.*

25 The court first observes that, consistent with UniRAM's  
26 proposed construction, a "logic circuit" is different from a  
27 "peripheral circuit." When discussing peripheral circuits, the  
28 '148 patent consistently refers to circuitry such as sense

1 amplifiers and decoders, which are outside the memory cells but  
2 within the memory device. See, e g, '148 patent at 2:19-21  
3 ("Peripheral circuits such as sense amplifiers, decoders, and  
4 precharge circuits are depend[ent] upon memory cell pitch"), 7:12-  
5 14 ("Each memory bank needs to have a full set of peripheral  
6 circuits"). When discussing logic circuits, the '148 patent  
7 consistently refers to logic components outside of the memory  
8 device. See, e g, '148 patent at 2:62-64 ("high density memory  
9 device placed on the same chip as high performance logic  
10 circuits"), 3:6-7 ("contradicting requirements between logic  
11 circuits and memory devices"). Although peripheral circuits  
12 contain "logic" components, that does not make them "logic  
13 circuits." Instead, the '148 patent consistently treats logic  
14 circuits and peripheral circuits as separate and non-overlapping  
15 entities. See, e g, 21:48-49 ("the transistors used for peripheral  
16 circuits and logic circuits").

17           Nonetheless, UniRAM's proposed construction is  
18 problematic because it defines logic circuit at a level of detail  
19 that is unsupported by the specification. UniRAM imports  
20 limitations that the specification never discusses — for example,  
21 the specification never mentions a microprocessor or ASIC.  
22 Moreover, the specification implicitly concedes that "logic  
23 circuits" are not necessarily high performance by using the phrase  
24 "high performance logic circuits." '148 patent at 2:63-64; see  
25 also Phillips, 415 F3d at 1314 (use of term "steel baffles"  
26 strongly implies that not all baffles are made of steel).

27 //

28 //

1           Accordingly, the court adopts a blend of the parties'  
2 constructions — a "logic circuit" is "a circuit outside of the  
3 memory device that performs some processing or controlling  
4 function." This construction distinguishes "logic circuits," which  
5 are outside of memory devices, with "peripheral circuits," which  
6 are within memory devices.

7           As a final matter, the court notes that the parties  
8 apparently want "logic circuit" and "logic-circuit" to share the  
9 same construction. Jt Cl Const, Ex B at 12. Because the term  
10 "logic-circuit" is only used on a few occasions and always as  
11 "peripheral logic-circuit," the court declines to construe  
12 separately the term "logic-circuit."

13  
14 2. "peripheral logic-circuit"

15           Claim 1 of the '229 patent includes the term "peripheral  
16 logic-circuit." UniRAM propounds a construction similar to its  
17 proposed construction for "logic circuit," and argues that "a  
18 'peripheral logic-circuit' is a type of 'logic circuit' (namely a  
19 'peripheral' one)." UniRAM Br (Doc #91) at 17. In particular,  
20 UniRAM explains that "a 'peripheral logic-circuit' is simply a  
21 'logic circuit' located outside of, but on the same substrate as, a  
22 memory circuit \* \* \* thereby forming an embedded memory device."  
23 Id at 30. MoSys construes peripheral logic-circuit as "[a] circuit  
24 outside of the memory array that performs some processing or  
25 controlling function;" TSMC adopts the same construction but omits  
26 the word "some" and changes "function" to "functions." Jt Cl  
27 Const, Ex B at 13. Under UniRAM's construction, the '229 patent  
28 covers only embedded DRAM; under MoSys's and TSMC's constructions,



1 the patent covers both embedded and stand-alone DRAMs.

2           The court agrees with UniRAM that the '229 patent  
3 pertains to embedded, and not stand-alone, memory technology, and  
4 therefore, MoSys's and TSMC's proposed constructions for  
5 "peripheral logic-circuit" are incorrect. The specification never  
6 discusses stand-alone DRAM, but discusses embedded technologies at  
7 length. '229 patent at 2:41-3:24 (discussing the difficulty in  
8 prior art embedded DRAM manufacturing and the novel approach  
9 employed in the invention), 20:16-24 (discussing the advantages  
10 obtained according to this invention as "[c]omparing with current  
11 art embedded memory technologies, the present invention simplifies  
12 the manufacture technology by more than 30%"), 22:2-19 (discussing  
13 the transistor properties of prior art embedded technology), 24:31-  
14 52 (discussing novel design methods to reduce effect of higher  
15 leakage current for transistors in embedded technology). The  
16 patent title, field of invention and various invention objectives  
17 all refer to embedded memory. Id at cover (Title: "High  
18 Performance Embedded Semiconductor Memory Device \* \* \*"), 1:15-19  
19 (Field of invention: "The present invention relates \* \* \*  
20 particularly to embedded memory devices \* \* \*"), 3:36-44 (Invention  
21 objectives: "to manufacture [embedded device] without using complex  
22 manufacture technology \* \* \* to make embedded DRAM to have the same  
23 performance as high-speed logic circuits \* \* \* to improve yield and  
24 reliability of embedded memory products). Moreover, the theme of  
25 manufacturing the DRAM memory cell using standard logic technology  
26 appears throughout the specification. A memory cell manufactured  
27 in this way would likely be part of an embedded, not stand-alone,  
28 DRAM. Id at 5:11-12 ("process step to manufacture a DRAM memory

1 cell by adding one masking step to standard logic technology"),  
2 17:48-52, 17:63-66, 19:48-65, 20:18-20 ("the procedures used to  
3 build the DRAM cell are existing procedures of standard logic  
4 technology, except one masking step and one plasma-etching step"),  
5 20:29-32. The specification also discusses the simultaneous  
6 manufacturing of memory cells and logic circuits. A memory cell  
7 manufactured in this way would be a part of an embedded, not stand-  
8 alone, DRAM. Id at 21:41-44 ("The word line transistor (1402) in  
9 the memory cell of the present invention has the same properties  
10 and it is manufactured in the same time as the transistors used for  
11 peripheral circuits and logic circuits.").

12 Nonetheless, MoSys and TSMC argue that this court cannot  
13 import limitations from the specification based on the patent  
14 title, invention objectives, field of invention and disclosed  
15 embodiments. But this argument overlooks the court's duty to  
16 interpret claims in light of the specification. The Federal  
17 Circuit has described the balance between these competing  
18 interests:

19 [The] balance turns on how the specification  
20 characterizes the claimed invention. In this  
21 respect, this court looks to whether the  
22 specification refers to a limitation only as a  
23 part of less than all possible embodiments or  
24 whether the specification read as a whole  
25 suggests that the very character of the  
26 invention requires the limitation be a part of  
27 every embodiment. For example, it is  
28 impermissible to read the one and only  
disclosed embodiment into a claim without  
other indicia that the patentee so intended to  
limit the invention. On the other hand, where  
the specification makes clear at various  
points that the claimed invention is narrower  
than the claim language might imply, it is  
entirely permissible and proper to limit the  
claims.

1 Alloc, Inc v ITC, 342 F3d 1361, 1370 (Fed Cir 2003) (internal  
2 citations omitted) (emphasis added). Here, the whole character of  
3 the invention is geared toward embedded technology. The patent  
4 title, field of invention, invention objectives and disclosed  
5 embodiments all relate to embedded, not stand-alone, DRAM.  
6 Accordingly, the court concludes that the claims in the '229 patent  
7 were directed only at embedded DRAM.

8           Nonetheless, UniRAM's proposed construction is  
9 problematic because, as with its proposed construction for "logic  
10 circuit," UniRAM defines peripheral logic-circuit at a level of  
11 detail that is unsupported by the specification. UniRAM once again  
12 imports limitations that the patent never discusses, such as the  
13 use of a microprocessor or ASIC.

14           Moreover, contrary to UniRAM's proposed construction, the  
15 specification teaches that "peripheral logic-circuit" encompasses  
16 both embedded logic circuits and peripheral circuits. When  
17 discussing threshold voltages and gate thicknesses, the  
18 specification states:

19           The word line transistor (1402) in the memory  
20 cell of the present invention has the same  
21 properties and it is manufactured in the same  
time as the transistors used for peripheral  
circuits and logic circuits.

22 '229 patent at 21:41-44. Claim 1 of the '229 patent states in  
23 relevant part:

24           1. A DRAM (dynamic random access memory) cell array  
25 supported on a substrate comprising \* \* \*  
26 said select-transistor-gate and said logic-circuit-gate  
having substantially a same thickness;  
27 said select-transistor for each of said memory cells  
28 having a select-transistor threshold voltage and each of  
said logic-transistors of said peripheral logic-circuit

1           having a logic-transistor threshold voltage wherein said  
2           select-transistor threshold voltage is substantially the  
          same as said logic-transistor threshold voltage.

3   Id at 25:29-26:11. The comparison in the specification between the  
4   properties of a word line transistor and the properties of a  
5   transistor used for peripheral and logic circuits finds a parallel  
6   in the comparison in claim 1 between the threshold voltage/gate  
7   thickness of a select-transistor and the threshold voltage/gate  
8   thickness of a logic-transistor in a peripheral logic-circuit.  
9   This parallelism is reinforced by the specification that  
10  alternatively refers to the "word line transistor (1402)" as  
11  "select transistor 1402." Id at 17:53-57. The parallel use of  
12  "peripheral logic-circuit" and "peripheral circuits and logic  
13  circuits," demonstrates that the former term encompasses peripheral  
14  circuits. Because courts should not construe patent terms to  
15  exclude disclosed embodiments, C R Bard, Inc, 388 F3d at 865, the  
16  court concludes that "peripheral logic-circuit" includes both  
17  embedded logic circuits and peripheral circuits.

18           Having determined that the patents-at-issue only relate  
19  to embedded technology, and that "peripheral logic-circuit"  
20  includes both peripheral circuits and logic circuits, the court  
21  construes "peripheral logic-circuit" to mean "a peripheral circuit  
22  and/or embedded logic circuit."

23  
24  3. "logic transistors"; "said logic transistors"

25           "Said logic transistors" appears in claim 21 of the '148  
26  patent. UniRAM asserts that the term means "[t]he previously-  
27  identified transistors designed and optimized to serve a logic  
28  function." MoSys asserts that the term lacks antecedent basis and

1 hence the claim is indefinite. If construed, however, MoSys and  
2 TSMC both contend that the term means the "transistors in a logic  
3 circuit." Jt Cl Const, Ex B at 18-19.

4           The construction of "said logic transistors" depends on  
5 the construction of "logic transistors." The court agrees with  
6 UniRAM that "said" merely means "previously identified." UniRAM Br  
7 at 31; id, Ex 21 at 6. Accordingly, the court first construes  
8 "logic transistors."

9           Throughout the specification, the patentee places  
10 adjectives in front of the term "transistor" to describe the  
11 function that the transistor has been designed to achieve. For  
12 example, the patent discusses "select transistors," which are  
13 designed to selectively activate the memory cell ('229 patent at  
14 19:31-44); "storage transistors," which are capacitors designed for  
15 storing a binary bit (id at 19:45-47) and "isolation transistors,"  
16 which are designed for isolating two adjacent logic transistors (id  
17 at 24:22-25). Applying this principle to "logic transistor," this  
18 term appears to describe a transistor that was designed and  
19 optimized to perform a logic function.

20           UniRAM's proposed definition for "said logic transistors"  
21 is function-based, which accords with how "logic transistor" is  
22 used in the patent. On the contrary, MoSys and TSMC's proposed  
23 definition is location-based, requiring "said logic transistor" to  
24 be within a logic circuit. This proposed construction conflicts  
25 with the specification, which states that logic transistors may be  
26 within memory cells: "[P]ractical memory devices using high  
27 performance logic transistor[s] in DRAM memory cells have been  
28 manufactured successfully." Id at 25:16-18. Because all parties

1 agree, and the court's earlier claim construction confirms, that  
2 logic circuits do not contain memory cells, defendants' location-  
3 based construction excludes this embodiment and hence is  
4 disfavored.

5           Nonetheless, MoSys asserts that the term lacks antecedent  
6 basis and is indefinite because this claim does not have a term  
7 "logic transistor" preceding "said logic transistor." UniRAM  
8 maintains that the antecedent phrase is "select transistor."  
9 UniRAM Br at 32 n16.

10           UniRAM's argument is bolstered by a passage in the  
11 specification of the '148 patent that teaches a method for  
12 manufacturing a DRAM cell array:

13           (f) forming logic transistors on the substrate  
14 having polysilicon gates covered by an insulation  
15 protective layer; (f) [sic] connecting the gate of a  
16 plurality of the logic transistors to a ground  
17 voltage thus defining a plurality of isolation  
18 transistors each separating two adjacent logic  
transistors wherein the insulation protective layer  
of the isolation transistors and the adjacent logic  
transistors defining open areas therein-between \* \*

19 '148 patent at 24:25-32 (emphasis added).

20           Other than using "said" rather than "the," the  
21 originally-filed version of claim 21 exactly mirrored the above  
22 passage. The patent office objected to that claim because "logic  
23 transistor" was not shown in a diagram, and rejected the claim  
24 because the patentee had apparently failed to provide an adequate  
25 written description how logic transistors are formed on the  
26 substrate. Behun Decl (Doc #106), Ex C, Office Action dated  
27 2/20/2003 for application 10/269,571 at 2 ¶¶ 1-2. In response, the  
28 patentee changed two references to "logic," corresponding to the

1 italicized words in the above passage, to "a plurality of select"  
2 and "select." Id, Office Action Response dated 8/20/03, at 7. The  
3 patentee explained that the amendments were done "to eliminate any  
4 claim related to the peripheral logic transistors. Instead, it is  
5 clearly defined as the select transistor of the memory cells, which  
6 is clearly shown and fully described all through the  
7 Specification." Id at 10-11.

8 A claim is not invalid for indefiniteness if its  
9 antecedent basis is present by implication. Cross Medical  
10 Products, Inc v Medtronic Sofamor Danek, Inc, 424 F3d 1293, 1319  
11 (Fed Cir 2005). The passage and prosecution history show that  
12 "select transistors" and "logic transistors" are used  
13 interchangeably in claim 21, and thus, "select transistors"  
14 provides an antecedent basis for "said logic transistors."  
15 Accordingly, the court concludes that the term "said adjacent logic  
16 transistors" is not indefinite. The court adopts UniRAM's  
17 construction of "said logic transistors" as "the previously-  
18 identified transistors designed and optimized to serve a logic  
19 function."

20  
21 4. "logic-transistor"

22 "Logic-transistor" only appears in claim 1 of the '229  
23 patent. UniRAM proposes that the term means "a transistor designed  
24 and optimized to serve a logic function;" MoSys proposes "[a]  
25 transistor in a peripheral logic-circuit;" and TSMC contends that  
26 this term requires no construction, but if construed, it means "a  
27 transistor in a logic circuit." Jt Cl Const, Ex B at 13.

28 //

1           The court observes that the patents use the terms "logic-  
2 transistor" and "logic transistor" interchangeably. See, e g, '229  
3 patent at 23:20-23 ("applying substantially same implant processes  
4 in forming the select-transistor and the logic-transistors wherein  
5 the select-transistor and the logic transistors having  
6 substantially a same threshold voltage." (emphasis added)). UniRAM  
7 and TSMC do not seem to think that the hyphen matters. Their  
8 proposed constructions for this term are in essence identical to  
9 their proposed constructions for "said logic transistor." Jt Cl  
10 Const, Ex B at 13, 18-19. This strongly suggests that the court  
11 should adopt the same construction for logic-transistor that was  
12 adopted for "logic transistor."

13           Moreover, there is no need to insert a location-based  
14 component into the definition for "logic-transistor," because the  
15 one claim in which this term appears already specifies that the  
16 "logic-transistor" is within a peripheral logic-circuit. '229  
17 patent at 25:29-26:11. Hence, MoSys's proposed construction that  
18 requires the logic-transistor to be within a peripheral logic-  
19 circuit is at best redundant. And TSMC's proposed construction  
20 that requires the logic-transistor to be within a logic circuit has  
21 no grounding in either the claim or in the specification.  
22 Accordingly, the court adopts UniRAM's proposed construction and  
23 defines "logic-transistor" as "a transistor designed and optimized  
24 to serve a logic function."

25  
26 5. "said adjacent logic transistors"

27           The term "said adjacent logic transistors" is in claim 21  
28 of the '148 patent. UniRAM asserts that this term means "logic



1 transistors adjacent to an isolation transistor." MoSys contends  
2 that the term is indefinite because it lacks antecedent basis, but  
3 to the extent it can be construed, MoSys agrees with TSMC that the  
4 term means "transistors in a logic circuit that are next to one  
5 another." Jt Cl Const, Ex B at 17.

6 As described above when construing "said logic  
7 transistor," "select transistor" provides an antecedent basis for  
8 "logic transistor" in claim 21. Accordingly, "adjacent select  
9 transistors" provides an antecedent basis for "said adjacent logic  
10 transistors." MoSys and TSMC's location-based construction  
11 requires the transistors to be in a logic circuit. For the reasons  
12 previously explained, the court rejects this construction.  
13 Moreover, even if defendants' construction were reformed to be no  
14 longer location-based, UniRAM's proposed construction better  
15 matches the language of claim 21, which states in part, "a  
16 plurality of isolation transistors each separating two adjacent  
17 select transistors." '148 patent at 27:46-48. Because "select  
18 transistor" and "logic transistor" are used interchangeably in  
19 claim 21, this phrase implies that logic transistors are separated  
20 by and adjacent to an isolation transistor. UniRAM's proposed  
21 construction best captures this meaning.

22  
23 6. "typical transistor of a logic circuit"

24 Because transistors are well-known to persons of ordinary  
25 skill in the art and because the court has already construed "logic  
26 circuit," there is no remaining ambiguity in this term and no need  
27 to construe it at this time.

28 //

1 7. "Gate"

2 "Gate" appears in claims 5, 12, 13 and 21 of the '148  
3 patent. UniRAM asserts that "gate" should mean "gate electrode."  
4 Jt Cl Const, Ex B at 11. MoSys and TSMC, without providing any  
5 reason, contend that the term is indefinite; to the extent the term  
6 can be construed, they contend it means "polysilicon gate  
7 electrode." Id; TSMC Br (Doc #99) at 32; MoSys Br (Doc #103) at  
8 53-54. Because the patentee expressly modified "gates" with  
9 "polysilicon" in claim 21 of the '148 patent, not all "gates" must  
10 be made of polysilicon. See Phillips, 415 F3d at 1314.  
11 Accordingly, the court adopts UniRAM's definition of gate as "gate  
12 electrode."

13  
14 8. "WL-transistor gate"

15 "WL-transistor gate" appears in claim 13 of the '148  
16 patent but does not appear in the specification except in a section  
17 paraphrasing the claim. '148 patent at 23:66-24:35. UniRAM  
18 contends that it means "the gate electrode in a memory cell  
19 transistor, which is connected to the word line (WL)." Jt Cl  
20 Const, Ex B at 31. MoSys and TSMC, again without providing any  
21 reason, contend that the term is indefinite; alternatively, they  
22 assert that the term means "the polysilicon gate electrode of the  
23 select transistor." Id.

24 As demonstrated presently, because "WL-transistor gate"  
25 is "amenable to construction," the term is not indefinite. Exxon  
26 Research and Engineering Co v United States, 265 F3d 1371, 1375  
27 (Fed Cir 2001). The court rejects UniRAM's construction because it  
28 introduces the term "memory cell transistor," which is not

1 mentioned anywhere in the patent. MoSys and TSMC's proposed  
2 construction better accords which claim 13, which states in part:  
3 "word-line (WL) select transistors each having a WL-transistor gate  
4 \* \* \*." '148 patent, at 27:1-3. In construing "gate," the court  
5 rejected defining that term using "polysilicon." The court  
6 therefore adopts a modified version of MoSys and TSMC's  
7 construction and defines "WL-transistor gate" as "the gate  
8 electrode of the word-line select transistor."

9  
10 9. "field oxide"

11 All three parties offer different definitions of "field  
12 oxide." UniRAM's proposed definition is "oxide that physically and  
13 electrically isolates active areas." Jt Cl Const, Ex B at 8. TSMC  
14 adds in the requirement that the field oxide must be "grown;" MoSys  
15 contends that the field oxide must be "grown" and "thick." Id.

16 Although the patent often uses field oxide to define a  
17 trench capacitor's edges, field oxide formation is only described  
18 once: "The first step is to define active area 1502, and grow  
19 isolation field oxide 1504 to separate those [sic] active area."  
20 '229 patent at 19:50-52. This intrinsic evidence indicates that  
21 the field oxide is isolated and is "grown." But this passage is  
22 one of many that describes alternative manufacturing procedures for  
23 the invention. Id at 19:52-21:4. Limiting field oxide to that  
24 which is "grown" would improperly import limitations from the  
25 specification to the claim. Phillips, 415 F3d at 1323.

26 Moreover, there is no intrinsic evidence suggesting that  
27 the field oxide must be "thick." Accordingly, the court adopts  
28 UniRAM's proposed construction.

1 10. "field oxide layer"

2 Having construed "field oxide," the court sees no reason  
3 to construe "field oxide layer," because the parties do not  
4 disagree over the meaning of "layer."

5  
6 11. "active area"

7 "Active area" appears in claims 3 and 4 of the '229  
8 patent and claims 3, 4, 5, 6, 24 and 25 of the '148 patent. MoSys  
9 and TSMC assert that "active area" is defined as "[t]he area where  
10 the claimed select transistor and the trench capacitor are formed,  
11 that area being bounded by the edges of the field oxide layer." Jt  
12 Cl Const, Ex B at 1. UniRAM contends that the active area is the  
13 "area bounded by the field oxide layer." Id.

14 The court adopts UniRAM's construction because it is  
15 simpler and more accurately reflects the disclosed embodiments.  
16 For example, one problem with MoSys and TSMC's definition is that  
17 the specification does not clearly delineate the select transistor  
18 gate's boundary. The specification states, "[T]he poly silicon  
19 word lines 1606 define the gates of the select transistors \* \* \*."  
20 '229 patent at 20:12-14. But Figure 15(c) shows these word lines  
21 traveling both in the active area 1502 and in the field oxide 1504.  
22 Because the specification never limits the gates to the active  
23 area, the select transistor gate could spill into the field oxide,  
24 making MoSys and TSMC's definition inaccurate.

25 More importantly, the complexity of MoSys and TSMC's  
26 construction is unnecessary, because the specification defines  
27 active area clearly and in concise terms: "The first step is to  
28 define active area 1502, and grow isolation field oxide 1504 to

1 separate those [sic] active area \* \* \*." Id at 19:50-52. And in  
2 seven of the eight claims in which active area appears, it is as  
3 "active area isolated and defined by edges of a field oxide layer,"  
4 "active area isolated by a field oxide," "active area isolated by  
5 said field oxide" or "active area isolated as an enclosed area by  
6 said filed [sic] oxide." Id at 26:16-17, 26:22-23 (claims 3 and  
7 4); '148 patent at 25:55, 25:64-65, 26:9-10, 28:20-21, 28:26-27  
8 (claims 3, 4, 5, 24 and 25). UniRAM's proposed construction  
9 captures this meaning better than MoSys and TSMC's construction.

10  
11 12. "SRAM (static random access memory)"

12 Because SRAM is a term well-known by persons of ordinary  
13 skill in the art, the court declines to construe it at this time.

14  
15 13. "surrounding"

16 The term "surrounding" appears only in claim 15 of the  
17 '148 patent. UniRAM asserts that the term means "encircling, in  
18 whole or in part." Jt Cl Const, Ex B at 26. MoSys contends that  
19 the term means "completely enveloping." Id. TSMC believes the  
20 term does not need any construction, and to the extent it does,  
21 TSMC supports MoSys's construction. Id.

22 The court adopts UniRAM's construction. First, it is not  
23 clear from claim 15 itself which definition is correct; the claim  
24 states in part, "forming a diffusion layer surrounding said  
25 trenches \* \* \*." '148 patent at 27:14. Moreover, the one time the  
26 specification refers to "surrounding," it does little more than  
27 paraphrase the claim. Id at 24:20-23. Nonetheless, the use of  
28 "diffusion layer" at other points in the specification is

1 instructive: "This constraint can be removed if a diffusion layer  
2 (1805) is deposited around the trench capacitor (1802) as  
3 illustrated by the cross-section diagram in FIG. 18(a)." Id at  
4 21:18-21. Figure 18(a) shows a cross-section of an embodiment in  
5 which the diffusion layer encircles a trench capacitor but does not  
6 "completely envelop" it. Id at fig 18(a). Hence, the court  
7 rejects MoSys's construction because it is too narrow to  
8 accommodate this embodiment, and adopts UniRAM's construction,  
9 which better accords with the specification.

10  
11 14. "trench[es]"

12 The term "trench" appears in three '229 patent claims as  
13 part of "trench capacitor" and in eleven '148 patent claims as part  
14 of "trench capacitor," "capacitor trench," "trench mask" and "said  
15 trench[es]." Three different constructions are offered for  
16 "trench[es]." UniRAM proposes that "trench[es]" means "a recess in  
17 the surface of a substrate." Jt Cl Const, Ex B at 29-30. TSMC  
18 requires that this recess be "deep," and MoSys additionally  
19 requires that the recess be in the "active area" of the substrate  
20 and that "the initial etching into the substrate is nearly  
21 perpendicular to the substrate surface." Id.

22 At no point do the claims or specification suggest that  
23 the initial etching must be nearly perpendicular. Moreover, the  
24 patents never indicate that the trench must be deep. On the  
25 contrary, the specification suggests that the storage capacitor for  
26 the invention is smaller than that of prior art DRAM cells. '229  
27 patent at 4:15-19, 17:46-50. Moreover, although MoSys and TSMC  
28 assert that figures 16(d) and 18(a) depict deep trenches, "the mere

1 fact that the patent drawings depict a particular embodiment of the  
2 patent does not operate to limit the claims to that specific  
3 configuration." Anchor Wall Systems, Inc v Rockwood Retaining  
4 Walls, Inc, 340 F3d 1298, 1306-07 (Fed Cir 2003).

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11 Accordingly, the court  
12 adopts UniRAM's definition of "trench[es]" as "a recess in the  
13 surface of the substrate."  
14

15 15. "trench capacitor"

16 "Trench capacitor" appears in three claims in the '229  
17 patent and nine claims in the '148 patent. The parties briefed  
18 this term together with the term "trench." The issue is whether a  
19 trench capacitor is formed wholly or partially within a trench.  
20 UniRAM argues that a trench capacitor includes a lateral component  
21 that is outside of the trench and connects to a transistor. UniRAM  
22 Br at 45. MoSys and TSMC instead contend that the lateral  
23 component is not part of the trench capacitor, which they assert  
24 must be formed wholly within the trench. MoSys Br at 43; TSMC Br  
25 at 33, n22. MoSys also asserts that UniRAM's proposed construction  
26 is too broad and includes non-trench capacitors such as a stacked  
27 capacitors, which only have a small portion within a shallow recess  
28 in the substrate. MoSys Br at 42-43.

1           The court agrees with MoSys and TSMC that a "trench  
2 capacitor" does not include the lateral components. In a section  
3 beginning with the "following advantages are obtained according to  
4 this invention," the patent states that "three edges of the trench  
5 capacitor are defined by field oxide" and the fourth edge "is  
6 defined by mask." '229 patent at 20:24-29. Accordingly, the  
7 trench capacitor cannot include the lateral components, which lie  
8 on top of the field oxide and do not share the same four edges as  
9 the trench. Figs 14(g), 18(b). And although the court does not  
10 limit the term "trench capacitor" to this particular embodiment,  
11 the court notes that the patent does not clearly indicate that a  
12 trench capacitor includes components outside of the trench.  
13 Moreover, UniRAM's broad definition creates ambiguity because the  
14 boundaries between the trench, lateral components and top electrode  
15 are unclear. Accordingly, the court adopts a modified version of  
16 TSMC's definition of "trench capacitor" that fits with the  
17 construction of "trench" above: "A capacitor formed entirely  
18 within a recess in the surface of a substrate."

19  
20 16. "said capacitor trench"

21           "Said capacitor trench" is used once in claim 6 of the  
22 '148 patent and was not briefed separately by the parties. Because  
23 "said" is commonly used to refer to previously-identified elements,  
24 "said capacitor trench" is properly construed as "previously-  
25 identified capacitor trench."

26           But what is problematic is that "capacitor trench" was  
27 never previously used in claim 6 or in independent claim 2 on which  
28 claim 6 is dependent. Although claim 2 describes the step of



1 "applying a capacitive-transistor trench mask for etching a  
2 plurality of trench capacitors \* \* \*," '148 patent at 25:45-50, it  
3 is unclear how this phrase provides an antecedent basis for "said  
4 capacitor trench." Does "said capacitor trench" implicitly define  
5 the trench within which the previously-mentioned "trench  
6 capacitors" were formed? Or is the patentee referring to the  
7 "trench capacitors" themselves? The specification provides no  
8 guidance to the court because the term "capacitor trench" is only  
9 used once in a section that paraphrases the claims. Id at 23:15-  
10 65. And UniRAM has not provided any guidance either — UniRAM's  
11 briefs do not address this term, and in the joint claim  
12 construction statement, UniRAM directs the court to its non-  
13 existent discussion of "capacitor trench." Jt Cl Const, Ex B at  
14 18. Accordingly, the court agrees with MoSys that the lack of  
15 antecedent basis for "said capacitor trench" renders that term  
16 indefinite.

17  
18 17. "threshold voltage"

19 The term "threshold voltage" appears in claim 1 of the  
20 '229 patent and claims 1 and 22 of the '148 patent. MoSys and TSMC  
21 contend that threshold voltage should be defined in terms of a  
22 specified current that operates under normal conditions. Jt Cl  
23 Const, Ex B at 27. UniRAM instead defines threshold voltage as the  
24 critical gate electrode to source electrode voltage that turns on  
25 the transistor. Id.

26 Contrary to MoSys's and TSMC's proposed construction, the  
27 specification never discusses how threshold voltage depends on  
28 current flow or operating conditions. But the specification does

1 discuss "[t]he threshold voltage of those depletion mode  
2 transistors" in the context of activating those transistors with  
3 gate select and drain select signals. '229 patent at 16:57-17:34.  
4 Because this intrinsic evidence is more consistent with UniRAM's  
5 construction, the court defines threshold voltage is "the critical  
6 gate electrode to source electrode voltage that determines whether  
7 a field effect transistor is on or off."

8  
9 18. terms with "substantially"

10 Five disputed terms contain "substantially:" (1) "said  
11 select-transistor threshold voltage is substantially the same as  
12 said logic-transistor threshold voltage," (2) "said select-  
13 transistor-gate and said logic-circuit-gate having substantially a  
14 same thickness," (3) "substantially a same [thickness]," (4)  
15 "substantially the same [threshold voltage]" and (5) "substantially  
16 all memory read errors." Jt Cl Const, Ex B at 19-22, 23-25. These  
17 terms appear in claims 1 and 5 in the '229 patent and claims 1, 13,  
18 14, 22 and 26 in the '148 patent. The court only construes the  
19 term "substantially" in each of these phrases because the other  
20 terms either are construed elsewhere in this order or are agreed  
21 upon by the parties.

22 For all terms except "substantially all memory read  
23 errors," UniRAM contends that "substantially" means "approximately,  
24 but not necessarily exactly." MoSys and TSMC instead propose that  
25 substantially means "identical except for differences that would  
26 necessarily result from the transistors being manufactured at the  
27 same time using the same process." Id.

1 For "substantially all memory read errors," UniRAM  
2 proposes a definition of "approximately all, but not necessarily  
3 all, memory read errors." Id at 25. MoSys's proposed construction  
4 is "[t]he number of read errors that an error code checking (ECC)  
5 and correction means of the prior art could correct." Id. TSMC  
6 asserts that this term does not need any construction, but if  
7 construed, TSMC proposes the same definition as MoSys but with  
8 "memory checking" replacing "error code checking (ECC)." Id.  
9 Neither MoSys nor TSMC provide any arguments in support of their  
10 proposed construction of this term.

11 Other than one section of the specification in which the  
12 claims are simply paraphrased, the specification uses  
13 "substantially" only once, stating "[t]he sense amplifier used in  
14 the present invention is substantially the same as typical sense  
15 amplifiers used in the prior art." '229 patent at 11:33-35.  
16 UniRAM's construction of "substantially" is consistent with this  
17 use of the term, unlike MoSys's and TSMC's proposed constructions.

18 Nonetheless, both MoSys and TSMC contend that their  
19 proposed constructions mimic the specification, which provides many  
20 embodiments that teach simultaneously fabricating the select and  
21 logic transistors. '229 patent at 21:41-44, 23:10-23. But by  
22 importing this limitation from the specification, MoSys and TSMC  
23 are asking the court to limit the claims to particular embodiments,  
24 which is something that the Federal Circuit has admonished district  
25 courts not to do. Phillips, 415 F3d at 1323.

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12 MoSys also notes that UniRAM adopts language similar to  
13 MoSys's construction in UniRAM's Patent L R 3-1 disclosure. Id at  
14 36-37. But this disclosure only addresses how MoSys allegedly  
15 infringes UniRAM's '229 patent. The disclosure does not address  
16 the scope of UniRAM's claims. In other words, UniRAM's particular  
17 description how MoSys infringes UniRAM's patent in this case does  
18 not mean that UniRAM is limited to that description in all cases.

19 MoSys also argues that UniRAM's construction would  
20 render the claim indefinite because a standard for measuring  
21 "substantial" is required to provide notice to a person of ordinary  
22 skill what is covered by the claims. Id at 39-40. But the patents  
23 do provide some measure of what "substantially" means, albeit  
24 indirectly. UniRAM admits that it distinguished between threshold  
25 voltages of 0.7 and 1.1 volts, and oxide thicknesses of 70 and 100  
26 angstroms. UniRAM Reply (Doc #118) at 19:18-28; '229 patent at  
27 21:39-22:44. Accordingly, the difference between two threshold  
28 voltages or thicknesses necessarily cannot be greater than or equal

1 to 0.4 volts or 30 angstroms, respectively, if the two values are  
2 "substantially the same."

3 Because substantially is not defined explicitly in the  
4 patent and does not appear to carry any special meaning in the  
5 relevant field, the court turns to the term's customary and  
6 ordinary meaning. Schumer v Laboratory Computer Systems, 308 F3d  
7 1304, 1311 (Fed Cir 2002) ("The proper approach is to construe the  
8 claim language using standard dictionary definitions, because here,  
9 the claims have no specialized meaning."). UniRAM's proposed  
10 constructions for "substantially" fit comfortably with the term's  
11 usage in the patent. These constructions also match the term's  
12 dictionary meaning. See, e g, Webster's Third New Intl Dictionary  
13 2280 (1981) (substantial[ly]: "being that specified to a large  
14 degree or in the main"); Black's Law Dictionary 1428-29 (6th ed  
15 1990) (substantially: "[e]ssentially; without material  
16 qualification; in the main; in substance \* \* \*"). And because  
17 there is no reason to think that the patentee intended to use  
18 "substantially" differently in different contexts, UniRAM's  
19 consistent definition for that term is preferable to defendants'  
20 piecemeal approaches. Accordingly, the court adopts UniRAM's  
21 constructions for the terms containing "substantially."

22  
23 19. "error code checking (ECC) and correction means"

24 "Error code checking (ECC) and correction means" appears  
25 in claim 5 of the '229 patent and claims 14 and 26 of the '148  
26 patent. The parties agree that this term is a  
27 "means-plus-function" limitation based on 35 USC § 112(6), which  
28 requires this court to define the claimed functions and then to

1 identify the corresponding structure(s) in the specification.  
2 Versa Corp v Ag-Bag Intern Ltd, 392 F3d 1325, 1328 (Fed Cir 2004).  
3 The parties also concur on the claimed function "checking and  
4 correcting substantially all memory read errors within a threshold  
5 error-detection-and-correction time." UniRAM Br at 46; MoSys Br at  
6 45; TSMC Br at 37.

7 But the parties disagree on whether the patent  
8 sufficiently describes a structure for the claimed function, and if  
9 so, what that structure is. UniRAM maintains that the  
10 corresponding structure is an "ECC circuit." TSMC and MoSys both  
11 contend that the term is indefinite, but to the extent the term can  
12 be construed, MoSys asserts that it should be limited to the ECC  
13 structure illustrated in figure 20(b). Jt Cl Const, Ex B at 6-8.

14 For a means-plus-function claim, "while it is true that  
15 the patentee need not disclose details of structures well known in  
16 the art, the specification must nonetheless disclose some  
17 structure. Stated differently, the testimony of one of ordinary  
18 skill in the art cannot supplant the total absence of structure  
19 from the specification." Default Proof Credit Card System, Inc v  
20 Home Depot USA, Inc, 412 F3d 1291, 1302 (Fed Cir 2005) (citation  
21 omitted). And "[a] structure disclosed in the specification  
22 qualifies as [a] 'corresponding' structure only if the  
23 specification or prosecution history clearly links or associates  
24 that structure to the function recited in the claim." Id at 1298.

25 Here, UniRAM cannot identify any corresponding structure  
26 in the specification that justifies broadly construing "error code  
27 checking (ECC) and correction means" to encompass any ECC circuit.  
28 The specification states "[t]he ECC circuit is well known to the

1 art, so we do not discuss it in further details." '229 patent at  
2 11:61-63. This disclosure provides no structure that can form the  
3 basis of a means-plus-function claim. And in any event, UniRAM has  
4 not linked this disclosure to the claimed function, so to grant  
5 UniRAM broad coverage here would ignore that the "duty to link or  
6 associate structure to function is the quid pro quo for the  
7 convenience of employing § 112, ¶ 6." Default Proof, 412 F3d at  
8 1298.

9           Nonetheless, the court also disagrees with MoSys and  
10 TSMC, who assert that the term is indefinite. Both MoSys and TSMC  
11 admit that at least some structure is provided by figure 20(b),  
12 which is a "simplified block diagram of a memory device equipped  
13 with ECC protection circuits." MoSys Br at 45, n26; TSMC Br at 38.  
14 In particular, figure 20(b) provides a high-level block diagram  
15 showing data memory 2001, ECC parity data 2003, ECC parity tree  
16 2005 and ECC correction logic 2007. '229 patent at figure 20(b).  
17 The accompanying discussion teaches how these elements operate, and  
18 how they relate to the claimed function. Id at 24:61-25:15 (e g,  
19 "In case there are corruption data, an ECC correction logic (2007)  
20 will find out the problem and correct the error so that the output  
21 data will be correct;" "When a memory device is equipped with an  
22 ECC circuit, it will correct most single-bit errors. As a result,  
23 the refresh time of the memory device is no longer dependent on the  
24 worst bit in the memory."). Hence, figure 20(b) discloses a  
25 structure that provides an adequate basis for the means-plus-  
26 function claim and that links to the claimed function.  
27 Accordingly, the court concludes that "error code checking (ECC)  
28 and correction means" corresponds to the ECC protection circuit

1 shown in figure 20(b), which includes ECC parity data 2003, ECC  
2 parity tree 2005 and ECC correction logic 2007.

3  
4 20. "threshold error-detection-and-correction time"

5 "Threshold error-detection-and-correction time" appears  
6 in claim 5 of the '229 patent and claims 14 and 26 of the '148  
7 patent. The specification never explicitly defines this term and  
8 only uses the term when paraphrasing the claims. '229 patent 23:4-  
9 9, 24:13-15, 24:50-53, 24:61-25:15. Both MoSys and TSMC contend  
10 that this term is indefinite; MoSys also asserts that to the extent  
11 the term can be construed, it means "the point at which the error  
12 correction scheme of the prior art can no longer overcome errors."  
13 Jt Cl Const, Ex B at 26; TSMC Br at 39-42. UniRAM proposes a  
14 highly-similar construction that defines the term as "the time past  
15 which the error correction scheme can no longer consistently and  
16 accurately correct errors." Jt Cl Const, Ex B at 26.

17 UniRAM's proposed construction is problematic because the  
18 "consistently and accurately" limitation is never mentioned in the  
19 specification. More importantly, UniRAM's construction seems  
20 indefinite because it adds a meaningless limitation to the claims.  
21 For example, after replacing "threshold error-detection-and-  
22 correction time" with UniRAM's proposed construction, each of the  
23 claims would read: "an error code checking [ECC] and correction  
24 means \* \* \* for checking and correcting substantially all memory  
25 read errors within the time past which the error correction scheme  
26 can no longer consistently and accurately correct errors." The  
27 phrases "checking and correcting substantially all memory read  
28 errors" and "consistently and accurately correct errors" both refer



1 to an ECC's effectiveness. Accordingly, when used together, either  
2 the former or the latter phrase is superfluous. Because a  
3 limitation cannot be construed out of the claims, UniRAM's proposed  
4 construction cannot be correct. Texas Instruments v United States  
5 ITC, 988 F2d 1165, 1171 (Fed Cir 1993).

6 MoSys's proposed construction suffers from the same  
7 indefiniteness problem. The specification notes that "[t]he ECC  
8 circuit [used in this invention] is well known to the art, so we do  
9 not discuss it in further details." '229 patent at 11:61-63.  
10 Accordingly, the terms "an error code checking [ECC] and correction  
11 means \* \* \* for checking and correcting substantially all memory  
12 read errors" and "the point at which the error correction scheme of  
13 the prior art can no longer overcome errors" both rely directly on  
14 the effectiveness of prior art ECCs.

15 But simply because UniRAM's and MoSys's proposed  
16 constructions are indefinite does not necessarily mean that the  
17 claim is "insolubly ambiguous" or that "no narrowing construction  
18 can properly be adopted." Honeywell Intl, Inc v ITC, 341 F3d 1332,  
19 1338-39 (Fed Cir 2003) (quoting Exxon Research, 265 F3d at 1375).  
20 Rather, UniRAM's expert, Carl Sechen, notes that "threshold error-  
21 detection-and-correction time" likely relates to a memory cell's  
22 refresh time, which is the time period since data was last fully  
23 written to the memory cell. UniRAM Br, Ex 3 ¶¶ 190-93. By  
24 improving the capability of a memory cell to correct errors, an ECC  
25 circuit allows a memory cell to have a longer refresh time,  $T_{ecc}$ ,  
26 as compared to the refresh time if there were no ECC,  $T_{min}$ :

27 //

28 //

1 When a memory device is equipped with an ECC  
2 circuit, it will correct most single-bit errors. As  
3 a result, the refresh time of the memory device is  
4 no longer dependent on the worst bit in the memory.  
5 Instead the device will \* \* \* function until the  
6 errors are more than what the ECC mechanism can  
7 correct. The refresh time (T<sub>ecc</sub>) is therefore  
8 higher than T<sub>min</sub> as shown in FIG. 20(a).

9 '229 patent at 25:9-14.

10 Accordingly, the specification supports modifying MoSys's  
11 construction so that "threshold error-detection-and-correction  
12 time" means the "maximum refresh time beyond which the ECC and  
13 correction means can no longer overcome errors." Because this  
14 definition imports the concept of a refresh time, constructing the  
15 term this way does not render it superfluous as used in the claims.

#### 16 IV

17 In sum, the court has construed many of the disputed  
18 terms of the '229 and '148 patents according to the intrinsic  
19 record and the patents' plain language. The court declined to  
20 construe some terms in these patents because their meaning was no  
21 longer ambiguous after the court had construed other related terms.

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Mark

United States District Chief Judge